NSSHNBO

SPDT SWITCH GaAs MMIC

FEATURES

- AEC-Q100 grade 1 qualified
- Control voltage V_{CTL(H)} = 3.0 V typ.
- Low insertion loss

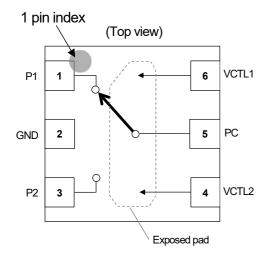
0.35 dB typ. @ f = 0.3 to 2.5 GHz 0.45 dB typ. @ f = 4.9 to 5.9 GHz 0.60 dB typ. @ f = 8.5 GHz

- High isolation
 28 dB typ. @ f = 0.3 to 2.5 GHz
 27 dB typ. @ f = 4.9 to 5.9 GHz
 18 dB typ. @ f = 8.5 GHz
- P-1dB = +31 dBm typ. @ f = 0.3 GHz, 2.5 GHz, 5.9 GHz
- Wide operating temperature -40 to +125°C
- Package with wettable flank ESON6-GC (1.6 x 1.6 x 0.78 mm typ., pin pitch 0.5 mm)
- RoHS compliant and Halogen Free, MSL1

■ APPLICATION

- 802.11 a/b/g/n/ac/ax and BT networks applications
- UWB (ultra-wide band) applications
- RKE applications
- General purpose switching applications

BLOCK DIAGRAM (ESON6-GC)



■ GENERAL DESCRIPTION

The NJG1801BKGC-A is an ultra-wide band SPDT switch for automotive suited for WiFi, Bluetooth, UWB applications and so on.

This switch features low insertion loss and high isolation covering up to 8.5 GHz.

ESON6-GC package with wettable flank structure corresponds to Automated Optical Inspection (AOI) which has strong demands from automotive customers.

TRUTH TABLE

"H" = $V_{CTL(H)}$, "L" = $V_{CTL(L)}$

VCTL1	VCTL2	ON Path
L	Н	PC-P1
Н	L	PC-P2

■ PIN CONFIGURATION

PIN NO.	SYMBOL	DESCRIPTION
1	P1	RF input/output
2	GND	Ground terminal
3	P2	RF input/output
4	VCTL2	Control signal input
4	VUILZ	terminal
5	PC	RF input/output
6	VCTL1	Control signal input
0	VOILI	terminal
Exposed pad	GND	Ground terminal

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PRODUCT NAME INFORMATION

<u>NJG1801B</u>	KGC	<u>-A</u>	<u>(TE3)</u>	
I		L	ı L	
Part number	Package	Auto	motive	Taping form

ORDERING INFORMATION

PART NUMBER	PACKAGE OUTLINE	RoHS	HALOGEN- FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ (pcs.)
NJG1801BKGC-A	ESON6-GC	Yes	Yes	SnBi	1801B A	5.4	3,000

ABSOLUTE MAXIMUM RATINGS

	(General conditions: $T_a = +25^{\circ}C$, $Z_s = Z_l = 50 \Omega$			
PARAMETER	SYMBOL	RATINGS	UNIT	
RF Input Power	PIN	+31 ⁽¹⁾	dBm	
Control Voltage	Vctl	6.0	V	
Power Dissipation ⁽²⁾	PD	1100	mW	
Operating Temperature	T _{opr}	-40 to +125	°C	
Storage Temperature	T _{stg}	-55 to +150	°C	

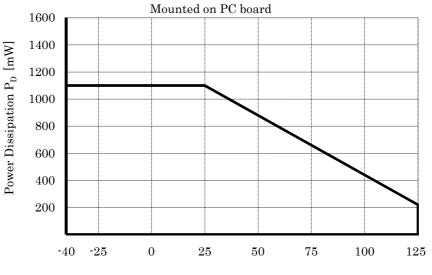
(1): $V_{CTL(L)} = 0 V$, $V_{CTL(H)} = 3.0 V$, on state port

(2): 4-layer FR4 PCB with through-hole (101.5 x 114.5 mm), Tj = 150° C

■ POWER DISSIPATION VS.AMBIENT TEMPERATURE

Please, refer to the following Power Dissipation and Ambient Temperature.

(Please note the surface mount package has a small maximum rating of Power Dissipation [P_D], a special attention should be paid in designing of thermal radiation.)



 $Power \ Dissipation-Ambient \ Temperature \ Characteristic$

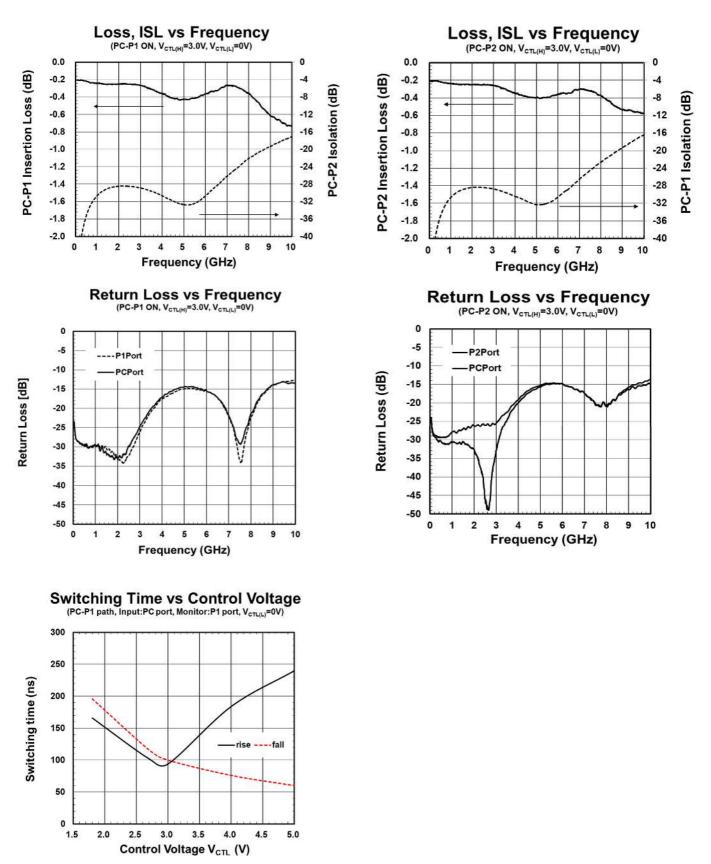
Ambient Temperature $Ta[^{\circ}C]$

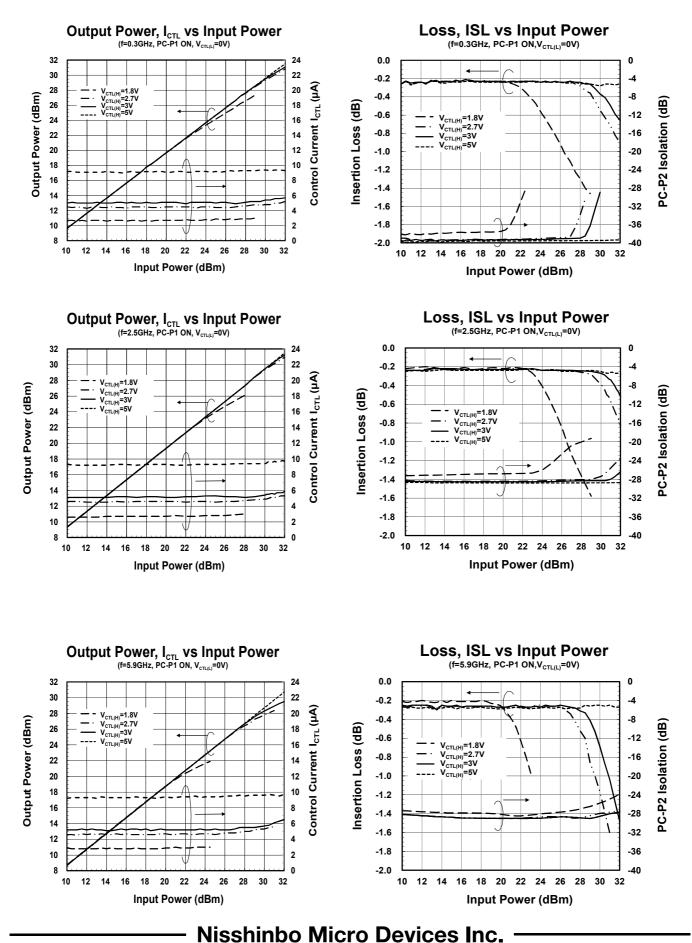
■ ELECTRICAL CHARACTERISTICS 1 (DC CHARACTERISTICS)

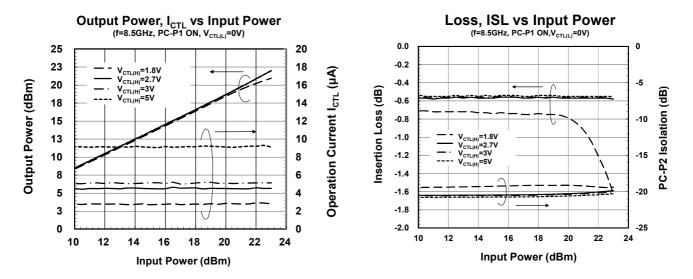
		(General conditions	: T _a = +2	5°C, with	applicati	on circuit)
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Control Voltage (HIGH)	Vctl(H)		1.8	3.0	5.0	V
Control Voltage (LOW)	Vctl(L)		-0.2	-	0.2	V
Control Current	Іст∟		-	5	10	μA

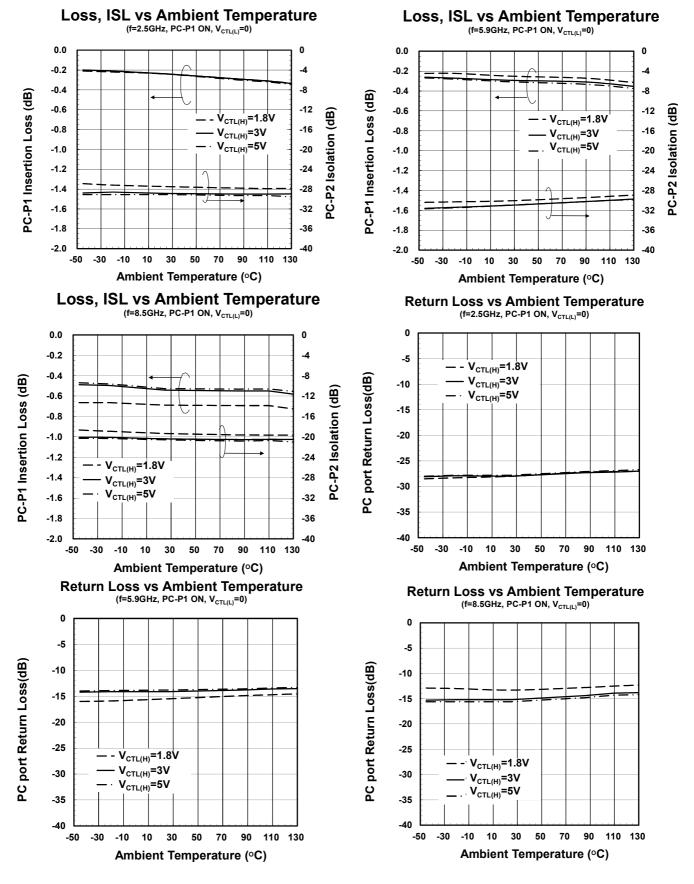
■ ELECTRICAL CHARACTERISTICS 2 (RF CHARACTERISTICS)

(Gener	al conditions:	$V_{CTL(H)} = 3.0 V, V_{CTL(L)} = 0 V, T_a = +25^{\circ}C, Z_s$	= Zı = 50	Ω , with a	applicatio	n circuit)
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Insertion loss1	LOSS1	f = 0.3 to 2.5 GHz	-	0.35	0.55	dB
Insertion loss2	LOSS2	f = 4.9 to 5.9 GHz	-	0.45	0.70	dB
Insertion loss3	LOSS3	f = 8.5 GHz	-	0.60	0.80	dB
Isolation1	ISL1	f = 0.3 to 2.5 GHz	25	28	-	dB
Isolation2	ISL2	f = 4.9 to 5.9 GHz	24	27	-	dB
Isolation3	ISL3	f = 8.5 GHz	16	18	-	dB
Return loss1	RL1	f = 0.3 to 2.5 GHz	18	28	-	dB
Return loss2	RL2	f = 4.9 to 5.9 GHz	10	15	-	dB
Return loss3	RL3	f = 8.5 GHz	10	14	-	dB
Input power at 1dB compression point1	P-1dB1	f = 0.3 to 2.5 GHz	+29	+31	-	dBm
Input power at 1dB compression point2	P-1dB2	f = 4.9 to 5.9 GHz	+28	+31	-	dBm
Input power at 1dB compression point3	P-1dB3	f = 8.5 GHz	+11	-	-	dBm
Switching time	Tsw	50% V _{CTL} to 10%/90% RF	-	100	300	ns

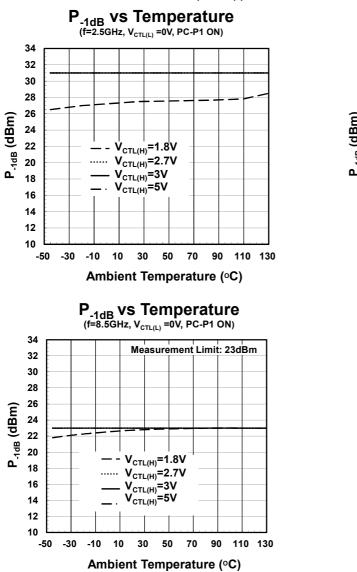


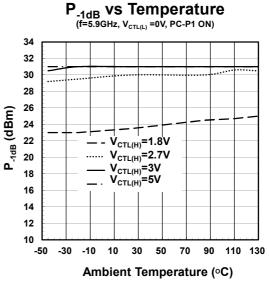




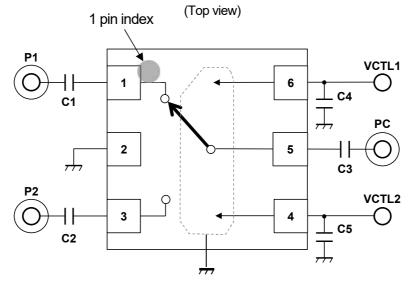


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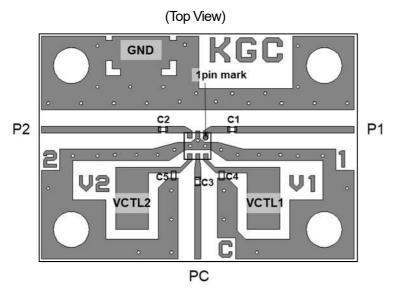
■ APPLICATION CIRCUIT



■ PARTS LIST

Part ID	Value	Notes
C1 to C3	1000 pF	GRM0335C1E102GA01D
C4 to C5	10 pF	GRM0335C1E100GA01D

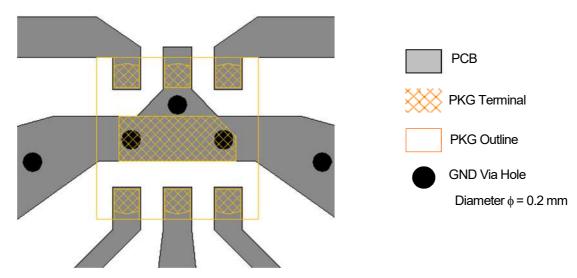
RECOMMENDED PCB DESIGN



PCB (FR-4): t = 0.2 mm MICROSTRIP LINE WIDTH = 0.4 mm (Z_0 = 50 Ω) PCB SIZE = 19.4 x 14.0 mm

L	Losses of PCB, capacitors and connectors, $Ta = +25^{\circ}C$				
	Frequency [GHz]	Loss [dB]			
=	0.3	0.14			
	2.4	0.38			
	2.5	0.39			
	4.9	0.59			
	5.9	0.73			
	8.5	0.91			

<PCB LAYOUT GUIDELINE>



PRECAUTIONS

- [1] The DC blocking capacitors (C1, C2, C3) should be placed at RF terminals. Please choose appropriate capacitance value at the application frequency.
- [2] For avoiding the degradation of RF performance, the bypass capacitors (C4, C5) should be placed as close as possible to VCTL terminals.
- [3] For good RF performance, GND terminal must be connected to PCB ground plane of substrate, and through -holes should be placed near the IC.
- [4] For good RF performance, exposed pad should be connected to PCB ground plane of substrate, and through -holes should be placed near the IC.

■ HANDLING PRECAUTIONS

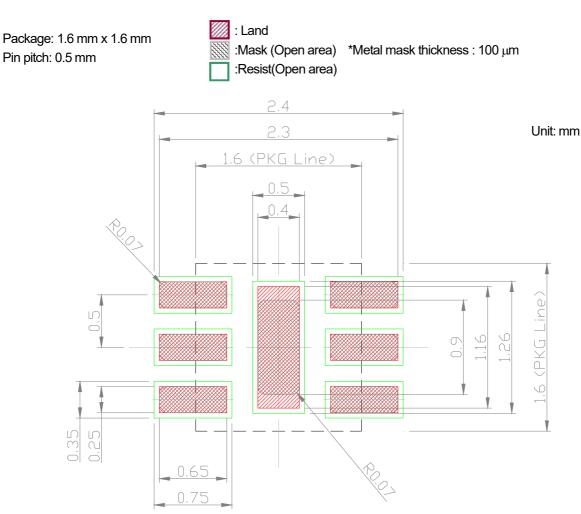
PIN NO.	SYMBOL	ESD RATINGS				
PIN NO.	STIVIDUL	Human Bo	dy Model ⁽¹⁾	Charged		
Commo	n terminal	Cround	I/O	Device		
Commo	lemina	Ground	1/0	Model ⁽²⁾		
1	P1	Class 1C	Class 2	Class C6		
2	GND	COM.	-	Class C6		
3	P2	Class 1C	Class 2	Class C6		
4	VCTL2	Class 0B	Class 0B	Class C6		
5	PC	Class 2	Class 2	Class C6		
6	VCTL1	Class 0B	Class 0B	Class C6		

(1): According to JEDEC JS-001

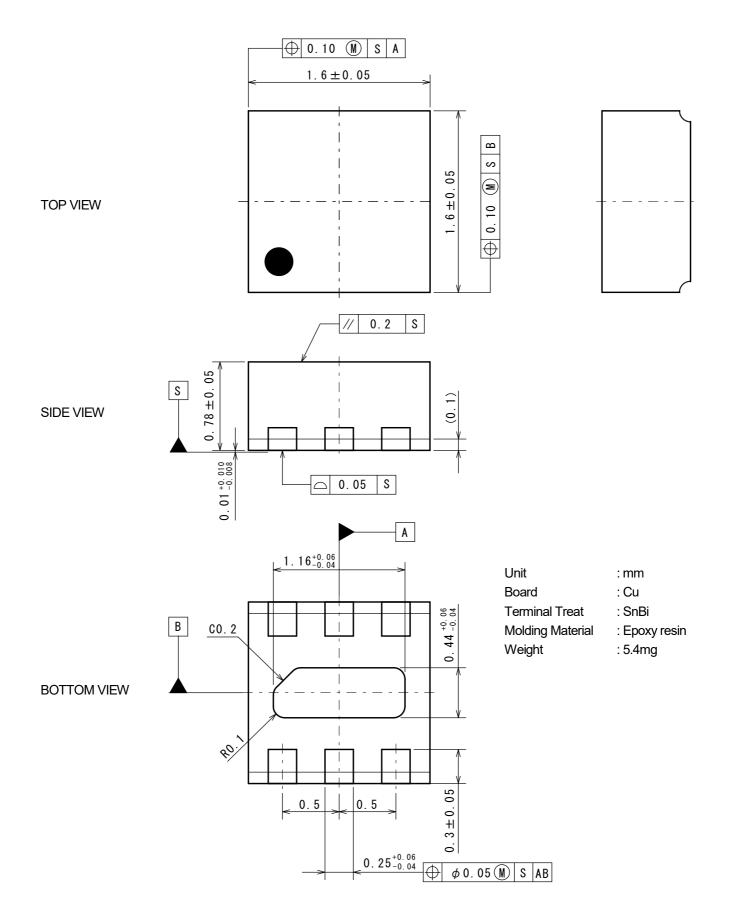
(2): According to JEDEC JS-002

CAUTION: This product may be damaged with electric static discharge (ESD) or spike voltage. Please handle with care to avoid these damages.

■ RECOMMENDED FOOTPRINT PATTERN (ESON6-GC PACKAGE) <Reference>



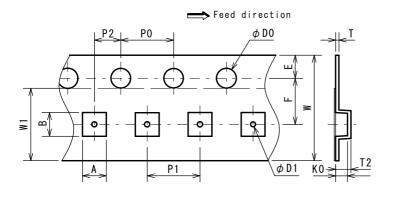
■ PACKAGE OUTLINE (ESON6-GC)



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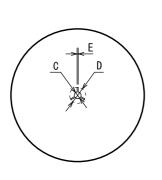
■ PACKING SPECIFICATION (ESON6-GC)

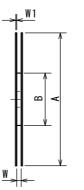
TAPING DIMENSIONS



SYMBOL	DIMENSION	REMARKS
A	1.80±0.05	BOTTOM DIMENSION
В	1.80±0.05	BOTTOM DIMENSION
DO	1.5 ^{+0.1}	
D1	0. 5 ^{+0.1}	
E	1.75±0.1	
F	3.5±0.05	
P0	4.0±0.1	
P1	4.0±0.1	
P2	2.0±0.05	
T	0.25±0.05	
T2	1.28±0.07	
KO	0.93±0.05	
W	8. 0 ^{+0.3} -0.1	
W1	5.5	THICKNESS 0.1max

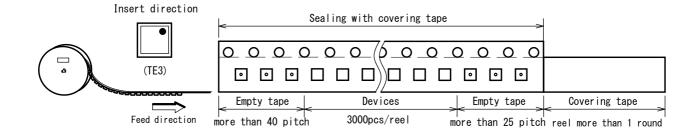
REEL DIMENSIONS



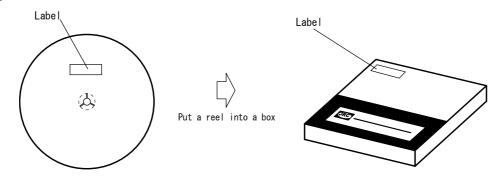


SYMBOL	DIMENSION	
Α	ϕ 180 $_{-1.5}^{0}$	
В	ϕ 60 $^{+1}_{0}$	
С	φ 13±0.2	
D	φ 21±0.8	
E	2±0.5	
W	9 ^{+0.3}	
W1	1. 2	

TAPING STATE



PACKING STATE



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UNIT: mm

■ REVISION HISTORY

	Date	Revision	Changes
	17.Nov.2021	Ver.1.3	Revised ELECTRICAL CHARACTERISTICS 1
			Revised RECOMMENDED PCB DESIGN
	5.Nov.2021	Ver.1.2	Revised RECOMMENDED FOOTPRINT PATTERN
	22.Dec.2020	Ver.1.1	Revised GENERAL DESCRIPTION
			Revised POWER DISSIPATION VS.AMBIENT TEMPERATURE (derating curve)
	20.Aug.2020	Ver.1.0	New Release

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 - Traffic control system
 - Combustion equipment

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 - 8-1. Quality Warranty Period

In the case of a product purchased through an authorized distributor or directly from us, the warranty period for this product shall be one (1) year after delivery to your company. For defective products that occurred during this period, we will take the quality warranty measures described in section 8-2. However, if there is an agreement on the warranty period in the basic transaction agreement, quality assurance agreement, delivery specifications, etc., it shall be followed.

8-2. Quality Warranty Remedies

When it has been proved defective due to manufacturing factors as a result of defect analysis by us, we will either deliver a substitute for the defective product or refund the purchase price of the defective product.

Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.

- 8-3. Remedies after Quality Warranty Period With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.
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- 13. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



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